



IEEE Letters on EMC Practice and Applications (L-EMCPA)



CALL FOR APPLICATION LETTERS



IEEE Letters on Electromagnetic Compatibility Practice and Applications (L-EMCPA) is a quarterly published letter journal that provides a rigorously peer-reviewed forum for rapid publication of **4-6 page letters** describing practice, lessons learned and applications of the disciplines electromagnetic compatibility (EMC) and signal and power integrity (SIPI) as well as all relevant methods to predict, assess and prevent electromagnetic interference (EMI) and increase device/product immunity.

Authors who submitted a Paper to the 2019 IEEE 4th GEMCCON, Stellenbosh, RSA are invited to submit an **application letter** of **four (4) up to six (6) pages** to the IEEE Letters on Electromagnetic Compatibility Practice and Applications (L-EMCPA). The submitted full paper will be subject of a full review. As the review of the submitted abstracts and the presentation at the EMC symposium are obtained as the first review cycle, the review is limited to one review cycle, only.

Authors are invited to submit manuscripts up to 6 pages in length, including title, author's affiliation, abstract, take home messages and figures via <https://mc.manuscriptcentral.com/l-emcpa-ieee>. A template is available on the EMC Society homepage (www.emcs.org) under publications.

Paper submission deadline: **15 October 2019**

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Employers/Companies of authors can place a free advertisement (1/8 page size) at the end of the issue.

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